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(54) APPARATUS AND ASSOCIATED METHODS

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(57) **ABSTRACT**

A substrate including a fluid reservoir and a connected fluid channel, the fluid reservoir positioned away from a component region of the substrate, the fluid channel configured to extend from the fluid reservoir to guide an electrically conductive fluid from the fluid reservoir at a reservoir end of the fluid channel through the fluid channel to a component end of the fluid channel, the component end extending to the component region of the substrate to enable the formation of an electrical connection to a connector of an electronic component appropriately positioned in the component region, formation of the electrical connection allowing the electronic component to be interconnected to other electronic components using one or more of the fluid reservoir and fluid channel.